## Session Program

March 17, 2022

# DTS-ST3 Meeting

# Technology Focus

# Thu, March 17

2:10 PM

3:40 PM

## Technology Focus: Bonding Technologies for Interconnect

**Session** | **Location:**

14:10 – 14:40 **Aluminum Wire Bonding & Aluminum Tab-Bonding**

**Speaker**

Carmen Simons

14:40 – 15:10 **Gold Stud-Bonding & Bump-Bonding**

**Speaker**

Michele Caselle

15:10 – 15:40 **Packaging Technologies at DESY - Flip-Chip Mounting**

**Speaker**

Sumera Kousar